

MAINTENANCE MANUAL FOR MVS RF BOARD 19D902032G1 (403-440 MHz) 19D902032G2 (440-470 MHz) 19D902032G3 (470-512 MHz)

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DESCRIPTION

The RF Board for the MVS radio consists of the following circuits:

- A frequency synthesizer for generating the transmit carrier frequency and the receive circuit first mixer injection frequency.
- The transmit exciter, PA and power control stages.
- The receive circuit front end, IF, and FM detector.
- Voltage regulators.

The 403-512 MHz range of UHF frequencies is covered by three groups of RF Boards:

19D902032 G1: 403-440 MHz

19D902032 G2: 440-470 MHz 19D902032 G3: 470-512 MHz

The RF Board is mounted in the bottom of the frame assembly. Refer to Combination Manual for a mechanical layout of the radio. Figure 1 provides a block diagram of the receive and transmit circuits. Figure 2 provides a block diagram of the synthesizer.

Transmit circuit adjustments for frequency, power and deviation are accessible from the topside of the board, as are IF alignment, second oscillator and audio level adjustments for the receive circuit. Chip components on the bottom of the board provide optimum RF performance, while being accessible for easy servicing by removing the "friction fit" bottom shields.

Selected use of sealed modules permits small board size as well as RF and mechanical protection for sensitive circuitry. Modules are not repairable and must be replaced if they are determined to be damaged.

CIRCUIT ANALYSIS

SYNTHESIZER CIRCUIT

The synthesizer generates all transmit and receive RF frequencies. The circuit uses a phase-locked VCO module U201 feeding a doubler circuit. While transmitting, the VCO operates at 1/2 the actual transmitter frequency (201.5-256.0 MHz to produce 403-512 MHz). While receiving, the VCO operates at 1/2 of the difference between the receiver frequency and the 45 MHz IF (179.0-233.5 MHz for 403-512 MHz).

Q201 doubles the VCO output frequency with input and output filters broadly fixed tuned to allow the VCO second harmonic to pass while rejecting all other frequencies. The doubled signal is amplified by Q201 to a level of $+10~\mathrm{dBm}$. This signal feeds the receiver mixer and is attenuated to $+3~\mathrm{dBm}$ by R202 to feed the transmitter exciter module.

The synthesizer frequency is controlled by the microprocessor on the Logic Board (A1). Frequency stability is maintained by a temperature compensated crystal controlled oscillator (TCXO) module. The oscillator has a stability of ± 5 PPM (0.0005%) over the temperature range of -30°C to +60°C and determines the overall frequency stability of the radio. An optional high stability ± 2.5 PPM oscillator module is available.

The VCO output is also buffered by Q204 to feed the divide by 128/129 dual modulus prescaler U205. The prescaler feeds the FIN input of the PLL U206. Within U206, the prescaled signal is further divided down to 6.25 kHz to be compared with a reference signal. This reference signal is derived from the 12.8 MHz TCXO module U204. U206 divides the 12.8 MHz TCXO down to the 6.25 kHz reference frequency.

Divider circuits in U206 are programmed by three inputs from the Logic Board (A1), which are buffered and inverted by transistors Q208, Q209, and Q210. The S ENABLE pulse (5 milliseconds) activates switch U202 to allow more rapid channel acquisition during channel changes.

A LOCK DET signal from the PLL goes to the microprocessor for processing to prevent transmission when the VCO is not on frequency and to provide an error message to the user. During receive, an unlocked synthesizer is indicated by E0 (Error 0) in the LCD and by a quickly pulsed alert tone. The microprocessor will continually try to reload the frequency information into the PLL until the synthesizer locks. During transmit, only a slower pulsed alert tone will be heard.

Once unlocked in transmit, the synthesizer will not be reloaded. The transmitter PTT must be unkeyed and then rekeyed to attempt to relock.

Audio modulation from Audio Board A3 is applied to the VCO module through DEVIATION ADJUST potentiometer R226. VCO TUNE potentiometer R218 adjusts the operating frequency range of the VCO by varying a negative bias from D202 and D203.

TRANSMITTER CIRCUIT

The transmitter consists of a fixed-tuned exciter module, a 10 Watt PA module, a pin diode switch, a low pass filter, a directional coupler, a power control circuit, and a transmit voltage switch.

Exciter Module

Figure 1 shows the synthesizer driving the receiver mixer at +10 dBm and is attenuated by R202 to +3 dBm for driving the exciter input. The exciter module A102 operates from a switched 8 volt supply. A different exciter module is required for each of the three band splits. No tuning is required. Both input and output ports operate at 50 ohms impedance. The exciter module provides typically 20 dB of gain and 200 mW of output power to drive the power amplifier module.

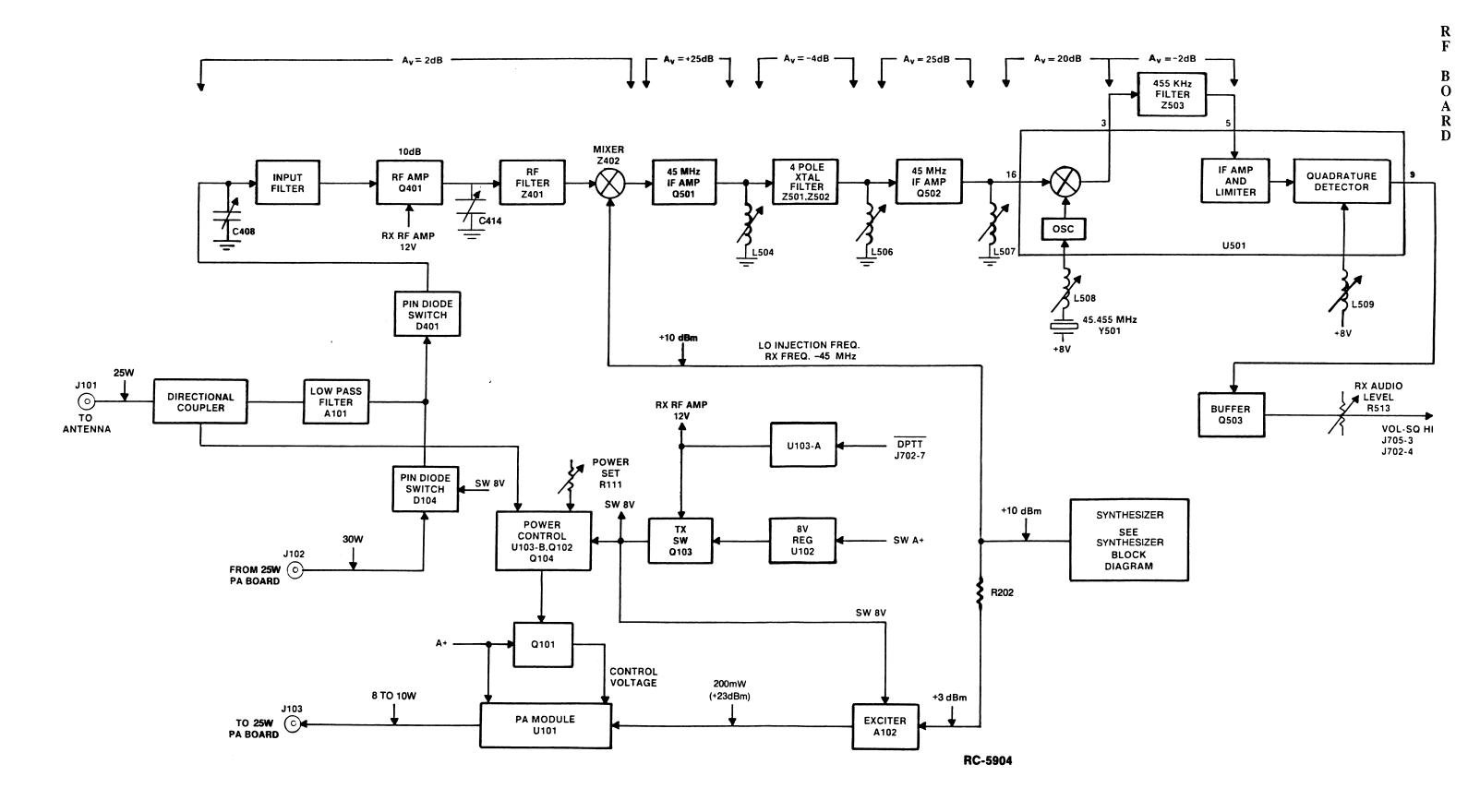
Power Amplifier Module

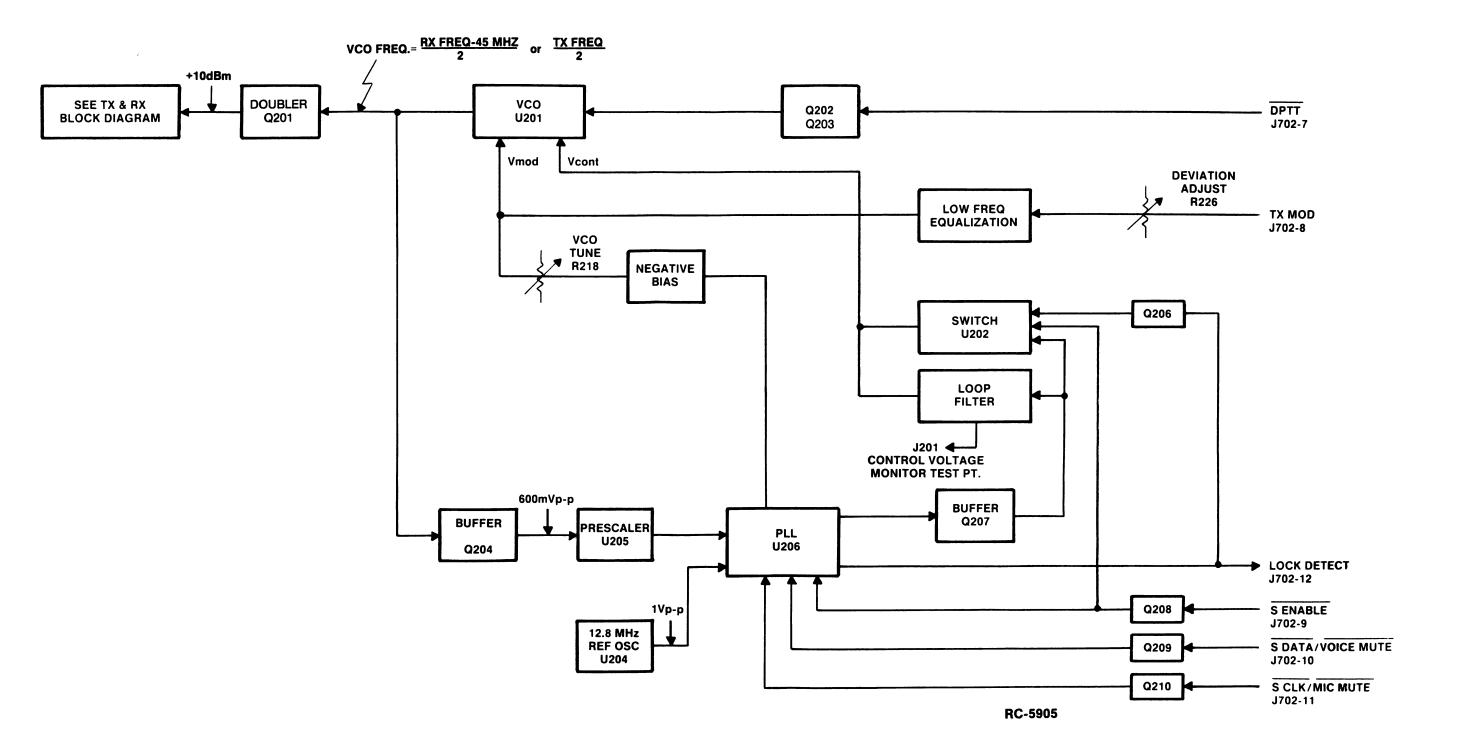
The PA module U101 requires a drive of 200 mW from the exciter module to deliver up to 10 Watts power output. The module is mounted to the rear heatsink. The PA module output drives the 25 Watt PA Board through J103. The power control circuit controls the PA module output power.

Pin Diode Switch. Low Pass Filter, and Directional Coupler

The output from the 25 Watt PA Board feeds transmit pin diode switch D104 through J102. In transmit, switched 8 volts is applied through L102, turning on pin diodes D104 and D401. The DC path is completed through R401 and R402 with the bias current set at about 40 mA. D104 couples the PA Board power from J102 to low pass filter A101. D401 provides a RF path to ground to protect the receiver input.

The low pass filter reduces the harmonic output from the transmitter. The low pass filter feeds the directional coupler, W101 and W102. The directional coupler provides a sample of transmitter power for the power control circuit. The coupler output feeds the antenna jack J101.





4

R

F

B

0

A

R

D

Power Control Circuit

The power control circuit samples the output power to the antenna to maintain a constant power level across the band. Also, a thermistor senses the heatsink temperature to throttle the power level down above 70°C. The circuit controls the supply voltage to one of the amplifier stages in the PA module U101.

The directional coupler (W101 and W102) provides a sample of transmitter power to diode D101. D101, R106, and C104 produce a positive DC voltage proportional to the transmitter output power level. This DC level feeds the (-) input of amplifier U103-B. Power set pot R111 and thermistor R118 determine the DC level to the (+) input of U103-B. U103-B amplifies the difference between the (-) and (+) inputs, forcing the output power level to equal the power set level by varying the drive to Q102 and Q101. Q101 supplies the control voltage to the PA module U101. For example, if the output power level begins to drop below the power set level, the output of U103-B increases positively, causing Q102 to conduct less. The base of Q101 rises, increasing the control voltage to the PA module, which increases the output power level back to the desired set level.

Q104, C123, and R105 improve the transient stability of the power control loop when the transmitter is keyed.

Transmit Switch

During transmit, the Logic Board (A1) microprocessor pulls the DPTT line low causing the output of U103-A to go low. Q103 turns on to supply SW 8V to the exciter module, the power control circuit and the pin diode switch. During receive, the output of U103-A supplies 12 volts to the receiver RF pre-amp Q401.

RECEIVER CIRCUIT

The dual conversion receiver circuit consists of a front end section, a 45 MHz first IF, and a 455 kHz second IF with a FM detector. All audio processing and squelch functions are accomplished on the Audio Board (A3).

Front End Section

RF is coupled from antenna jack J101 through the directional coupler and the low pass filter to pin diode D401. In transmit, SW 8V is applied through L102, turning on pin diodes D104 and D401, with the DC path completed through R401 and R402. D401 provides a RF path to ground for the receiver input while in transmit. In receive, D401 is off allowing RF to pass by D401 unattenuated.

The RF pre-amplifier is a dual gate FET with a 2 pole preselector filter and 2 pole output filter. The input filter consists of L402, L403 and associated capacitors. These components form a top coupled resonator filter. The input impedance level is 50 ohms while the output is loaded by the FET input impedance. Capacitor C408 is tuned for a flat bandpass response. The output matching filter consists of L404, L405, and associated capacitors. R410 helps establish a consistent impedance at the filter input. C414 is tuned for a flat bandpass response. The output filter matches Q401 to a 50 ohm impedance to terminate Z401. Z401 is a fixed tuned three pole bandpass filter covering a 20 MHz segment of the operating frequency band split.

The mixer, Z402, is a doubly balanced diode mixer. This mixer is driven by a local oscillator signal of +10 dBm or greater to provide good inter-modulation performance, spurious performance, and local oscillator isolation. The mixer conversion loss is typically about 6 dB.

45 MHz IF

The first 45 MHz IF amplifier transistor Q501 is a junction FET operated in the common gate mode. This configuration offers a typical input impedance of 75 ohms. The output circuitry is tuned by L504 and loaded to provide the proper source termination for the four pole crystal filter which follows.

The output of the crystal filter is matched by second IF amplifier transistor Q502. This port is also tuned by L506 and loaded to provide the proper filter termination. Transistor Q502 is a dual gate FET operating at a bias current of about 10 milliamps. The output of Q502 is tuned by L507 for maximum gain at 45 MHz and is loaded by the 2nd mixer in the U501 chip. This Q502 stage has a relatively high input and output impedance and needs high isolation within the active device. The dual gate FET provides the isolation required.

Converter/IF/Detector IC

IF IC U501 is a MC3361 chip. Pins 1 and 2 connect to an internally biased oscillator transistor. The external circuitry of this oscillator transistor includes crystal Y501 and forms an oscillator circuit operating at 45.455 MHz. The frequency of this third mode oscillator is adjusted by inductor L508. The oscillator drives the internal balanced mixer. The 45 MHz IF signal is translated to 455 kHz and appears at Pin 3 of U501. This IF signal is filtered by 6 pole ceramic filter Z503 and drives the internal 455 kHz amplifier and limiter. The limited 455 kHz in turn drives an internal quadrature detector. The phase shift network needed by the quadrature detector is

provided by inductor L509. The audio output port is Pin 9 on U501. Inductor L509 is adjusted for maximum audio output level. The audio signal at Pin 9 is filtered by resistor R512 and capacitor C519 to reduce IF feedthrough. Buffer amplifier Q503, drives audio potentiometer R513. This allows a VOL/SQ HI signal whose amplitude may be set for proper system operation using R513.

Power Distribution

Unswitched 13.8 Volts (A+) is supplied to the RF Board through connector J704 and feeds the power control transistor Q101, the PA module U101, and 20V transient suppressor D105. D105 protects the radio from noise spikes and other overvoltage transients appearing on the input power cable.

Switched 13.6 Volts (SW A+) is supplied to the RF Board through J702 and J705 and feeds regulators U102, U207, and U502. U102 supplies 8 Volts to the transmitter switch, the synthesizer 5 Volt regulator U203, and the Logic Board (A1) through J702. U207 supplies 8.3 Volts to the synthesizer. U502 supplies 8 Volts to the receiver.

SERVICE NOTES

TRANSMITTER CIRCUIT

Most transmitter circuit problems can be isolated by checking the TX power gains shown in Figure 1 - RX and TX Block Diagram. The 25 watt PA Board may be bypassed by placing a jumper cable between J103 and J102 on the RF Board. The PA module U101 is capable of producing 10 watts output.

Transmitter DC measurements

- 1. First ensure that DPTT is low when the mic PTT is keyed low.
- 2. Check for approximately 8 volts at L105 feeding the Exciter Module. If not present, troubleshoot the TX switch circuitry, Q103 and U103.
- Check for approximately 7 volts across resistors R401 and R402. If not present, check the pin diodes D104 and D401 and the conduction path from R401 to the TX switch Q103.
- 4. Check for an adjustable voltage of 0 to 12 volts on pin 2 of the PA module U101. At maximum power, with Power Set adjustment R111 fully clockwise, pin 2 should be at 12 volts. If not present, check the power control circuitry: U103, Q101, Q102, and Q104.
- Check for 13.6 volts on pins 3 and 4 of the PA module U101, and ensure a good mechanical and electrical ground from the PA module to the bracket and casting.

RECEIVER CIRCUIT

To isolate a receiver circuit problem refer to the Receiver Circuit Symptoms and Checks chart below.

RECEIVER CIRCUIT SYMPTOMS AND CHECKS

SYMPTOMS	CHECKS
No Audio	1. U502 regulator
	2. The level and frequency of the first mixer injection frequency
	3. The level and frequency of the second mixer injection frequency
4. Quadrature detector circuit	
	5. Quadrature detector coil tuning
Poor SINAD	1. Consult Figure 1 - RX and TX Block Diagram for RX stage gains
	and troubleshoot
	2. Input cable
	3. PIN Diode switch is shorted.
Distorted Audio	Both mixer injection frequencies
	2. Quadrature detector coil tuning
	3. Crystal filter source and load tuning
	4. Z503: 455 kHz ceramic filter

SYNTHESIZER CIRCUIT

Synthesizer troubleshooting consists of first checking for the proper DC levels, then determining if the proper waveforms are present and checking individual modules.

DC Analysis

8.3 Vdc is supplied by regulator U207 and serves as the biasing voltage for transistor circuits Q204, Q206, Q207, Q208, Q209, and Q210. Resistor R207 decouples the 8.3 volts for use in the VCO module U201. The 10 milliamp current drain of this module results in approximately 6.5 volts DC on Pin 4. Transistor Q201 also draws approximately 25 milliamps, resulting in a collector voltage of 3.7 volts DC at the junction of resistor R204 and capacitor C201. Lack of VCO RF output will modify this voltage.

Regulator U203 uses the 8 volts from transmitter regulator U102 to generate 5 volts for U204 and U205.

Waveforms

Waveforms associated with the synthesizer were measured with a 10 megohm, 30 pF probe. Use DC coupling (see Figures 3-8).

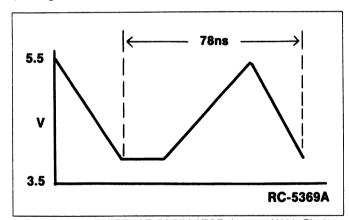


FIGURE 3 - REFERENCE OSCILLATOR (Input to U206, Pin 2)

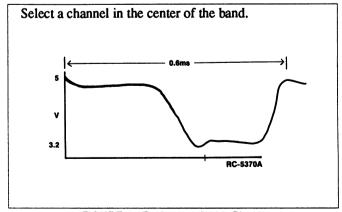


FIGURE 4 - F_{IN} (Input to U206, Pin 10)

The top of the ramp is approximately 0.8 Volt DC greater than the control voltage on PD out, Pin 17. A channel in the center of the band is shown.

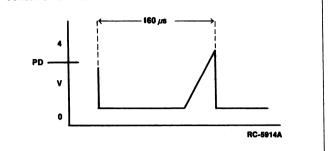


FIGURE 5 - RAMP (Generated in U206 and appears on Pin 15)

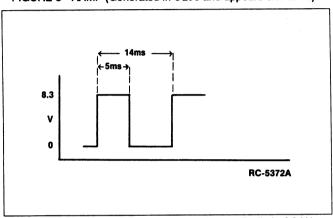


FIGURE 6 - S ENABLE (Input to U206, Pin 13) (Radio in SCAN on a single channel)

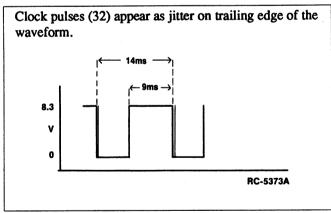


FIGURE 7 - S CLOCK (Input to U206, Pin 12) (Radio in SCAN on a single channel)

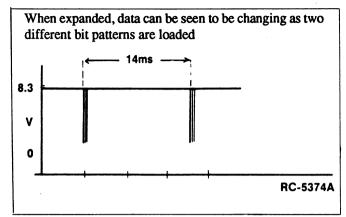


FIGURE 8 - S DATA (Input to U206, Pin 11) (Radio in SCAN on a single channel)

Module Isolation

Reference Oscillator U204:

Look for a waveform similar to the reference (Figure 3) on Pin 2. If waveform is not present, the oscillator module is probably defective.

VCO U201:

Connect a DC power supply to Pin 3. With 2.5 volts DC on pin 3, the output of U201 (pin 5) should be approximately 197 MHz. With 6.5 volts DC on pin 3, the output should be approximately 212 MHz. These values are correct for the 440-470 MHz split, with the ranges 179-197 MHz and 212-233 MHz being correct for the lower and upper split, respectively.

Power output of the VCO can be measured by connecting a coax directly to the module, between pin 5 and ground. The output should be approximately 0 dBm with C237 still connected in the circuit. In transmit, a negative bias should exist on pin 1. If not present, check Q202, Q203, and C206 before removing the VCO.

Prescaler U205:

Connect pin 3 of the VCO to 4.5 volts DC. With the radio in receive, monitor the frequencies of the VCO at the connection of capacitor C210 and resistor R211. DC short pin 1 of U205 to ground to cause divide by 129 to occur. The frequency output at pin 3 should be the VCO frequency divided by 129. Tie pin 1 to pin 7 (5 volts) to cause divide by 128 to occur. Check pin 3 to verify that this occurs. Improper division may indicate a defective prescaler.

Bilateral Switch U202:

The bilateral switch is used to short around parts of the loop filter during channel scan. A shorted (to ground or adjacent gate) gate may be isolated by comparing voltages through the loop filter to those of a functioning radio. Defective gates might be suspected when the radio does not change frequency quickly enough.

Phase-Lock-Loop U206:

There are no other specific checks which aid in evaluation of U206. Usually, it is suspected only if all other checks are OK. Before changing, inspect chip components for mechanical damage and check resistances through the loop filter.

Transistor O201:

After checking for proper DC operation, measure the frequency and gain from the VCO, pin 5 to R202/C203. The gain should be approximately 10 dB at 2 times the VCO frequency.

PA MODULE REPLACEMENT

To Remove PA Module U101

- Unsolder the four leads from U101, using either solder removal braid, or a mechanical de-soldering tool. These leads are fragile and can be bent very easily. Do NOT unsolder the shield that wraps around the module.
- Remove the RF Board from the radio chassis assembly. Refer to the disassembly procedure provided in the Service Section. Carefully slide the module out of the shield, and away from the board.

To Install PA Module U101

- 1. Apply some silicone grease to the metal side of the replacement module.
- Carefully insert the four leads from the module into the four corresponding PWB holes, and slide the module into the shield. Do NOT solder the leads yet.

3. Slide the RF Board assembly back into the radio frame. Reinstall all hardware, harnesses, cables, etc. Replace all screws.

4. Install the two PA bracket screws before solder ing the four module leads. Trim excess wire.

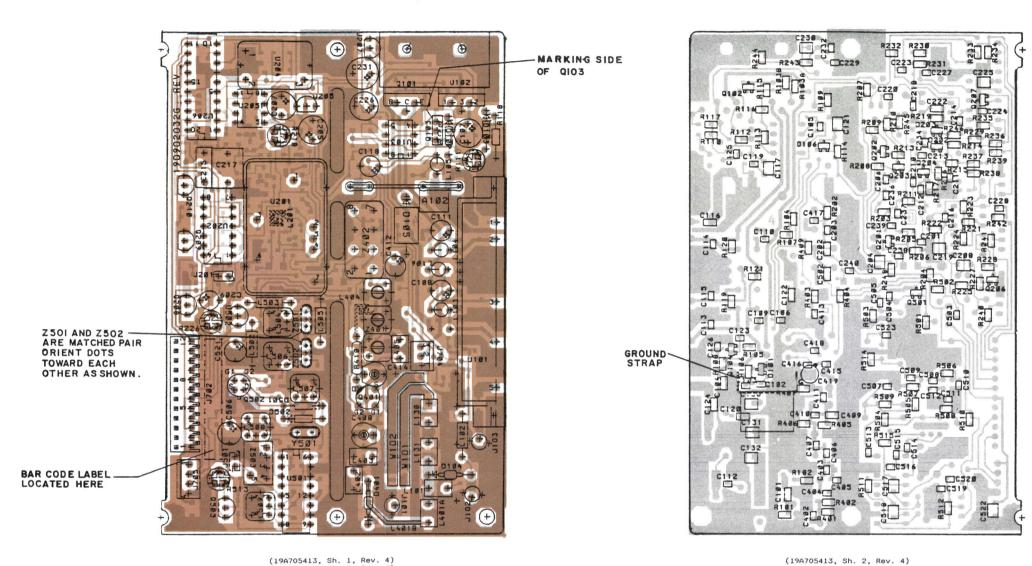
R F

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R D



GE Mobile Communications



1. 2, Rev. 4)

VIEW FROM BACKSIDE

LEAD IDENTIFICATION FOR D201



IN-LINE
TOP VIEW
NOTE: CASE SHAPE IS
DETERMINING FACTOR FOR
LEAD IDENTIFICATION.

LEAD IDENTIFICATION FOR G208, G209, G210, & G503



IN-LINE
TOP VIEW
NOTE: CASE SHAPE IS
DETERMINING FACTOR FOR
LEAD IDENTIFICATION.

LEAD IDENTIFICATION FOR U203, U207 & U502

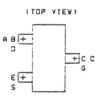


TOP VIEW

NOTE: CASE SHAPE IS
DETERMINING FACTOR FOR
LEAD IDENTIFICATION.

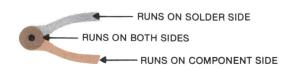
IN-LINE

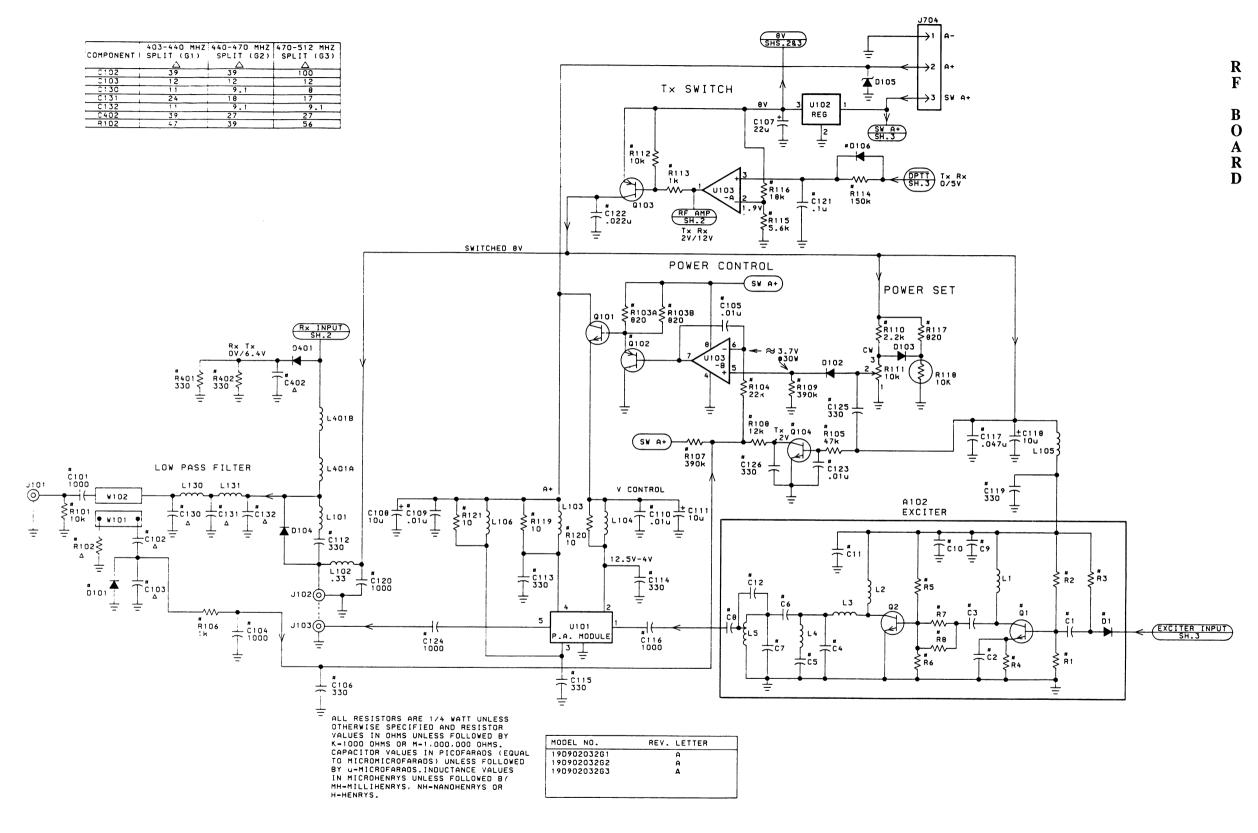
LEAD IDENTIFICATION FOR (SOT) TRANSISTORS AND DIODES



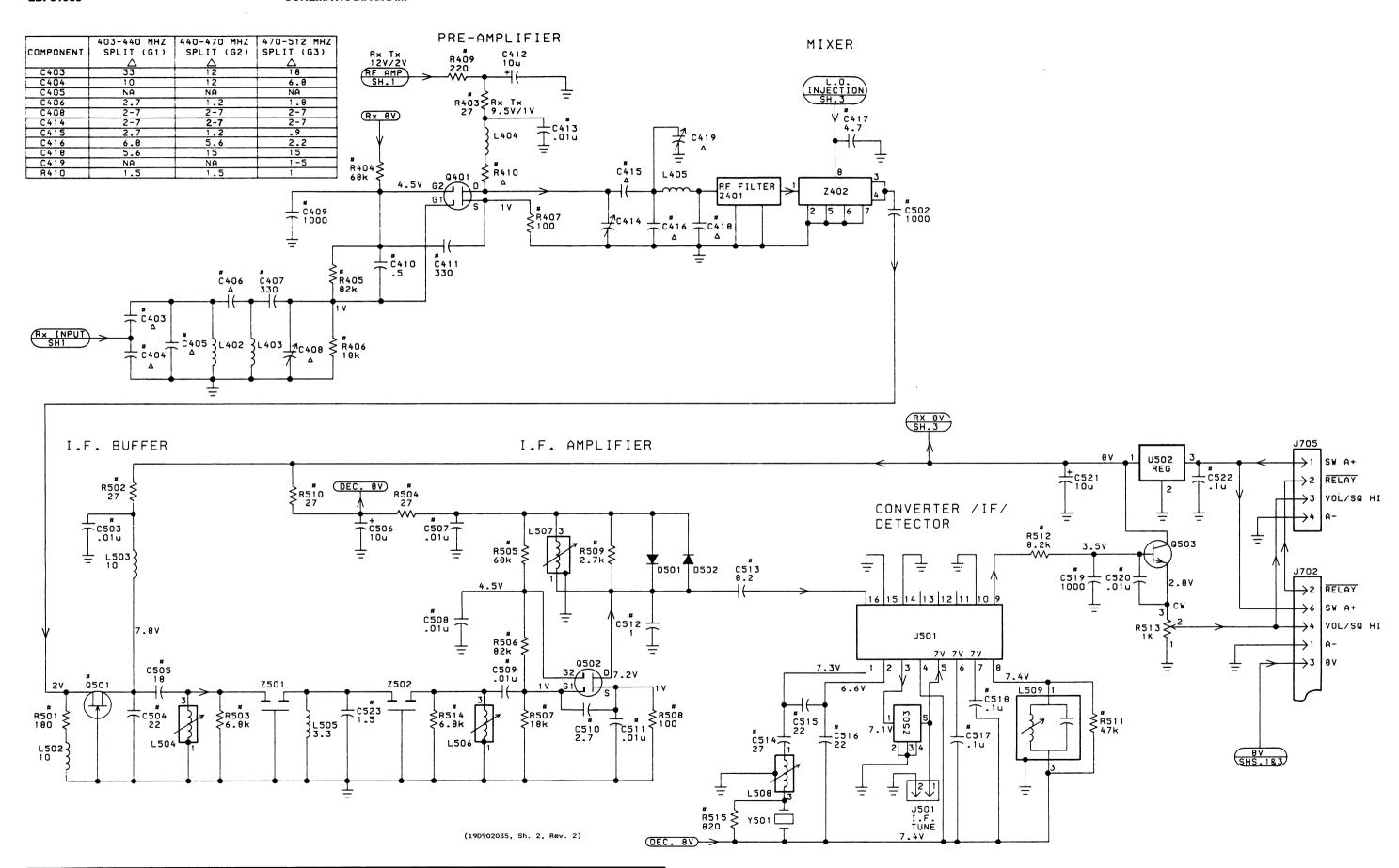
RC-7275

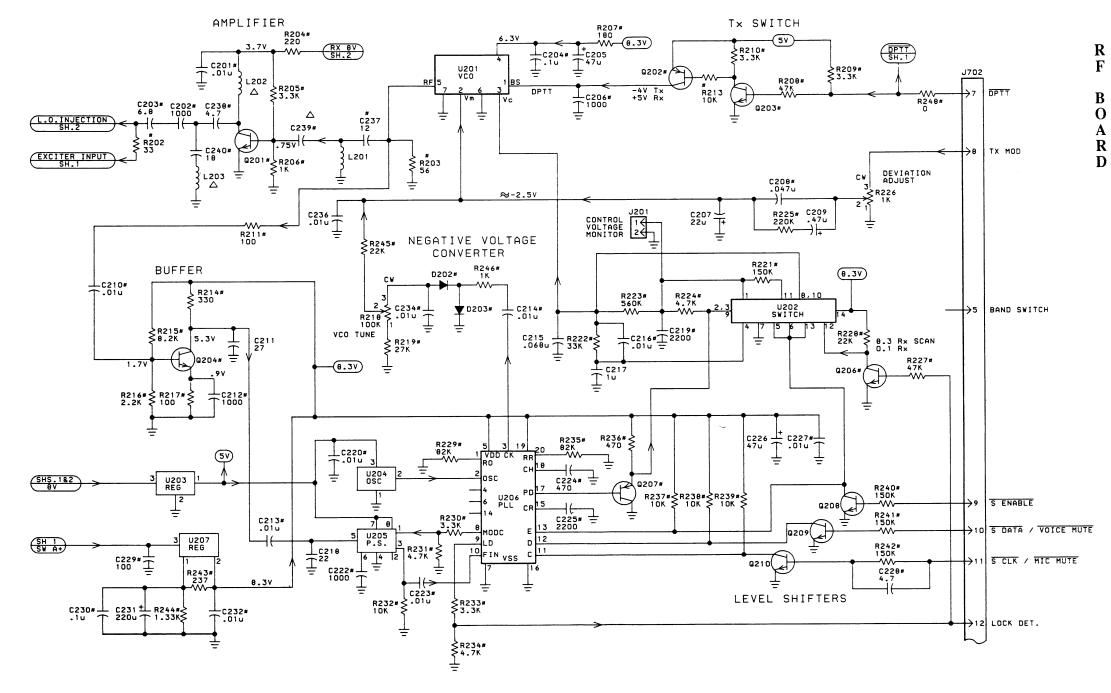
MADE FROM 19D902032 REV. 2





(19D902035, Sh. 1, Rev 4)



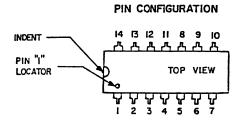


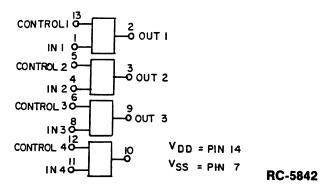
COMPONENT		440-470 MHZ SPLIT (G2) △	SPLIT (G3)
L202	27NH	27NH	22NH
L203	27NH	27NH	22NH
C239	8.2	8.2	6.8

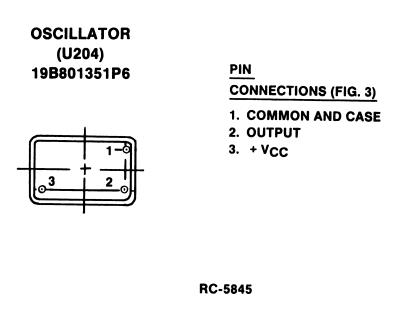
(19D902035, Sh. 3, Rev. 1)

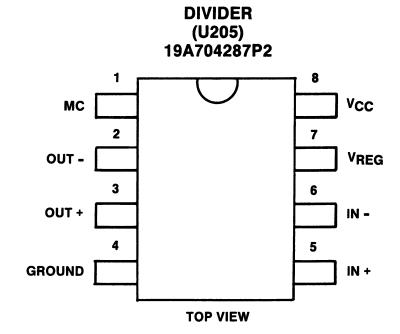
LBI-31933 IC DATA

QUAD BILATERAL SWITCH (U202) 19A700029P44

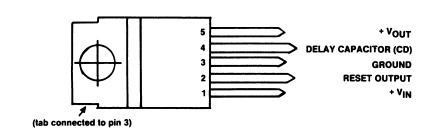




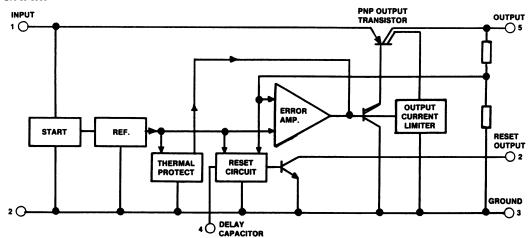




VOLTAGE REGULATORS (U203) 19A704971P1



BLOCK DIAGRAM



RC-5854

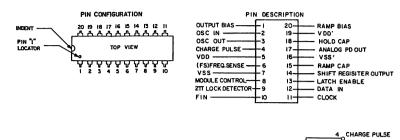
ICDATA

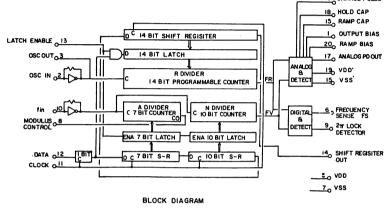
LBI-31933

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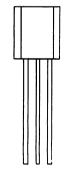
PHASE-LOCK-LOOP MODULE (U206) 19B800902P4







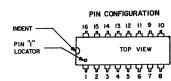
VOLTAGE REGULATOR (U207) 19A701999P4

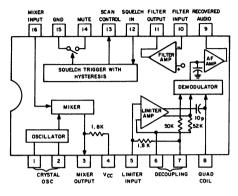




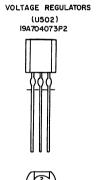
PIN 1 ADJUST PIN 2. OUTPUT PIN 3. INPUT

IF AMPLIFIER AND DETECTOR (U501) 19A704619P1





BLOCK DIAGRAM



BOTTOM VIEW
PIN I - OUTPUT
PIN 2 - GROUND
PIN 3 - INPUT

RC-5289

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LBI-31933 PARTS LIST

PARTS LIST

RF BOARD 19D902032G1 403-440 MHz 19D902032G2 440-470 MHz 19D902032G3 470-512 MHz TSSUE 3

SYMBOL	GE PART NO.	DESCRIPTION
A102		TRANSMIT EXCITER BOARD 19C851643G1 403-440 MHz 19C851643G2 440-470 MHz 19C851643G3 470-512 MHz
		CAPACITORS
Cl and C2	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/`C.
C3 *	19A702061P17	Ceramic: 12 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM/ $^{\circ}$ C. (Used in G1).
C3	19A702061P13	Ceramic: 10 pF +5%, 50 VDCW, temp coef 0 +30 PPM/`C. (Used in G2).
С3	19A702061P11	Ceramic: 6.8 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 60 PPM/ $^{\circ}$ C. (Used in G3).
C4	19A702061P13	Ceramic: $10 \text{ pF} \pm 5$ %, 50 VDCW , temp coef $0 \pm 30 \text{ PPM/}^{\circ}\text{C}$. (Used in G1).
C4	19A702061P11	Ceramic: 6.8 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 60 PPM/ $^{\circ}$ C. (Used in G2 & G3).
C5	19A702061P61	Ceramic: 100 pF \pm 5%, 50 VDCW, temp coef 0 \pm 30 PPM/ $^{\circ}$ C. (Used in G1).
C5	19A702061P45	Ceramic: $47 \text{ pF} \pm 5$ %, 50 VDCW , temp coef $0 \pm 30 \text{ PPM/}^{\circ}\text{C}$. (Used in G2 % G3).
C6	19A702061P10	Ceramic: 5.6 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 60 PPM/ $^{\circ}$ C. (Used in G1).
C6	19A702061P9	Ceramic: 4.7 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 60 PPM/ $^{\circ}$ C. (Used in G2 & G3).
C7	19A702061P12	Ceramic: 8.2 pF \pm 0.5 pF, 50 VDCW, temp coef 0 \pm 60 PPM/ $^{\circ}$ C. (Used in G1).
С7	19A702061P11	Ceramic: 6.8 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM/^C. (Used in G2 & G3).
C8 * thru C10	198702061P77	Ceramic: $470 \text{ pF} \pm 5$, 50 VDCW, temp coef $0 \pm 30 \text{ PPM/}^{\circ}\text{C}$.
cll	19A702052P14	Ceramic: 0.01 uF <u>+</u> 10%, 50 VDCW.
C12 *	19A702061P12	Ceramic: 8.2 pF \pm 0.5 pF, 50 VDCW, temp coef \pm 60 PPM/ $^{\circ}$ C. (Used in G1).
	-	DIODES
D1	19A702525P2	Silicon.
Ll		
L2	198800891P6	(Part of PWB 19C851644P1). Coil, RF: .084 uH; sim to Paul Smith SK-890-1.
L3 thru L5		(Part of PWB 19C851644P1).
Q1	19A704708P2	Silicon, NPN; sim to NEC 2SC3356.
Q2	19A701940P1	Silicon, NPN; sim to MRF-559.
		RESISTORS
R1	19B800607P471	Metal film: 470 ohms <u>+</u> 5%, 200 VDCW, 1/8 w.
R2	19B800607P222	Metal film: 2.2K ohms <u>+</u> 5%, 200 VDCW, 1/8
R3	19B800607P102	Metal film: 1K ohms <u>+</u> 5%, 200 VDCW, 1/8 w.
R4	19B800607P330	Metal film: 33 ohms +5%, 200 VDCW, 1/8 w.
R5	198800607P272	Metal film: 2.7K ohms ±5%, 200 VDCW, 1/8 w.
R6 R7	19B800607P331 19B800607P100	Metal film: 330 ohms <u>+</u> 5%, 200 VDCW, 1/8 w. Metal film: 10 ohms <u>+</u> 5%, 200 VDCW, 1/8 w.
and R8	!	<u>-</u>

SYMBOL	GE PART NO.	DESCRIPTION
010:	10.7000	
C101	19A702061P99	Ceramic: 1000 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C.
C102	19A702061P41	Ceramic: 39 pF +5%, 50 VDCW, temp coef 0 +30 PPM/'C. (Used in Gl).
C102	19A702061P37	Ceramic: 33 pF +5%, 50 VDCW, temp coef 0 +30 PPM/'C. (Used in G2).
C102	19A702061P61	Ceramic: 100 pF +5%, 50 VDCW, temp coef
C103	19A702061P17	0 ±30 PPM/`C. (Used in G3).
		Ceramic: 12 pF +5%, 50 VDCW, temp coef 0 +30 PPM/`C.
C104	19A702061P99	Ceramic: 1000 pF +5%, 50 VDCW, temp coef 0 +30 PPM/'C.
C105	19A702052P14	Ceramic: 0.01 uF +10%, 50 VDCW.
C106	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/\cdot\cdot\cdot\cdot\cdot\cdot\cdot\cdot
C107	19A701534P8	Tantalum: 22 uF +20%, 16 VDCW.
C108	19A703314P10	Blectrolytic: 10 uF -10+50% to1, 50 VDCW;
C109	19A702052P14	sim to Panasonic LS Series. Ceramic: 0.01 uF +10%, 50 VDCW.
and Cll0	198/02032714	Ceramic: 0.01 uF +10%, 50 VDCW.
C111	19A703314P10	Electrolytic: 10 uF -10+50% tol, 50 VDCW;
		sim to Panasonic LS Series.
Cll2 thru	19A702061P73	Ceramic: 330 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM/`C.
C114	198702061872	Coronice 220 pp 459 50 ypgs 4
C115	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G2).
C116	19A702061P99	Ceramic: 1000 pF +5%, 50 VDCW, temp coef 0 +30 PPM/`C.
C117	19A702052P22	Ceramic: 0.047 uF ±10%, 50 VDCW.
C118	19A703314P10	Electrolytic: 10 uF -10+50% tol, 50 VDCW;
C119	19A702061P73	sim to Panasonic LS Series.
CITY	194/020612/3	Ceramic: 330 pF +5%, 50 VDCW, temp coef 0 +30 PPM/ C.
C120	19A702061P99	Ceramic: 1000 pF +5%, 50 VDCW, temp coef 0 +30 PPM/ C.
C121	19A702052P26	Ceramic: 0.1 uF ±10%, 50 VDCW.
C122	19A702052P28	Ceramic: 0.022 uF ±10%, 50 VDCW.
C123	19A702052P14	Ceramic: 0.01 uF +10%, 50 VDCW.
C124	19A702061P99	Ceramic: 1000 pF +5%, 50 VDCW, temp coef
C125	19A702061P73	0 +30 PPM/'C. Ceramic: 330 pF +5%, 50 VDCW, temp coef
and C126	25	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/'C.
C130	19A705108P14	Mica: 11 pF ±5%, 500 VDCW.(Used in G1).
C130	19A705108P12	Mica: 9.1 pF ±5%, 500 VDCW. (Used in G2).
C130	19A705108P11	Mica: 8.2 pF ±5%, 500 VDCW. (Used in G3).
C131	19A705108P22	Mica: 24 pF ±5%, 500 VDCW. (Used in G1).
C131	19A705108P19	Mica: 18 pF <u>+</u> 5%, 500 VDCW. (Used in G2).
C131	19A705108P200	Mica: 17 pF ±5%, 500VDCW. (Used in G3).
C132	19A705108P16	Mica: 13 pF +5%, 500 VDCW. (Used in G1).
C132 *	19A705108P12	Mica: 9.1 pF ±5%, 500 VDCW. (Used in G2,G3).
C201	19A702052P14	Ceramic: 0.01 uF ±10%, 50 VDCW.
C202	19A702061P99	Ceramic: 1000 pF +5%, 50 VDCW, temp coef
C203	19A702061P11	0 ±30 PPM/`C
		0 <u>+</u> 60 PPM/`C.
C204	19A702052P26	Ceramic: 0.1 uF +10%, 50 VDCW.
C205	19A701534P17	Tantalum: 47 uF <u>+</u> 20%, 10 VDCW.
C206	19A702052P5	Ceramic: 1000 pF +10%, 50 VDCW.
C207	19A701534P8	Tantalum: 22 uF +20%, 16 VDCW.
C208	19A702052P22	Ceramic: 0.047 uF <u>+</u> 10%, 50 VDCW.
C209	19A701534P3	Tantalum: 0.47 uF <u>+</u> 20%, 35 VDCW.
C210	19A702052P14	Ceramic: 0.01 uF +10%, 50 VDCW.
C211	19A702061P33	Ceramic: $27 \text{ pF} \pm 5\%$, 50 VDCW, temp coef $0 \pm 30 \text{ PPM/}^{\circ}\text{C}$.
C212	19A702052P5	Ceramic: 1000 pF +10%, 50 VDCW.

SYMBOL	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO.	DESCRIPTION
C213 and	19A702052P14	Ceramic: 0.01 uF <u>+</u> 10%, 50 VDCW.	C411	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/ C.
C214 C215	19A700004P1	Matallized polyectors 0.068 up +109 62 Upcu	C412	19A703314P10	Electrolytic: 10 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series.
C215	19A702052P14	Metallized polyester: 0.068 uF +10%, 63 VDCw. Ceramic: 0.01 uF +10%, 50 VDCw.	C413	19A702052P14	Ceramic: 0.01 uP ±10%, 50 VDCW.
C217	19A700004P11	Metallized Polyester: 1.0 uF ±10%, 63 VDCW.	C414	19A702168P1	Variable, ceramic: 2 to 7 pF, 100 VDCW;
C218	19A702061P33	Ceramic: 27 pF +5%, 50 VDCW, temp coef 0 +30 PPM/°C. (Used in Gl).	C415	19A702236P11	sim to JPD DV2SN7A. Ceramic: 2.7 pF +0.25 pF, 50 VDCW, temp coef 0 +30 PPM/C. (Used in Gl).
C218	19A702061P29	Ceramic: 22 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/`C. (Used in G2,G3).	C415	19A702236P7	O +30 PPM/ C. (Used in GI). Ceramic: 1.2 pF +.25 pF, 50 VDCW, temp coef 0 +30 PPM/ C. (Used in G2).
C219	19A702061P93	Ceramic: 2200 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM/`C.	C415	19A702236P5	Ceramic: 0.9 pF ±.1 pF, 50 VDCW, temp coef 0 +30 PPM/°C. (Used in G3).
C220	19A702052P14	Ceramic: 0.01 uF <u>+</u> 10%, 50 VDCW.	C416	19A702236P21	Ceramic: 6.8 pF +0.5 pF, 50 VDCW, temp coef
C222	19A702061P99	Ceramic: 1000 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM/^c.	C416	19A702236P19	0 <u>+60 PPM/'C. (Used in G1).</u> Ceramic: 5.6 pF <u>+</u> .5 pF, 50 VDCW, temp coef
C223 C224	19A702052P14 19A702061P77	Ceramic: 0.01 uF ±10%, 50 VDCW. Ceramic: 470 pF ±5%, 50 VDCW, temp coef	C416 *	19A702061P5	0 ±30 PPM/'C. (Used in G2). Ceramic: 2.2 pF ±0.5 pF, 50 VDCW, temp coef
C225	19A702061P93	0 <u>+</u> 30 PPM/`C. Ceramic: 2200 pF +5%, 50 VDCW, temp coef	C417	19A702061P9	0 +120 PPM/'C. (Used in G3). Ceramic: 4.7 pF +0.5 pF, 50 VDCW, temp coef
		0 <u>+</u> 30 PPM/`C.		194702061910	0 +60 PPM/`C.
C226 C227	19A701534P17 19A702052P14	Tantalum: 47 uF ±20%, 10 VDCW. Ceramic: 0.01 uF ±10%, 50 VDCW.	C418		Ceramic: 5.6 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM/`C. (Used in G1).
C228	19A702061P9	- Ceramic: 4.7 pF +0.5 pF, 50 VDCW, temp coef 0 +60 PPM/C.	C418 *	19A702061P21	Ceramic: 15 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G2,G3).
C229	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/^C.	C419	19B800873P8	Variable, ceramic: 1 to 5 pF, 150 VDCW; sim to Johanson 9621. (Used in G3).
C230	19A702052P26	Ceramic: 0.1 uF +10%, 50 VDCW.	C502	19A702061P99	Ceramic: 1000 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM/`C.
C231	19A703314P2	Tantalum: 220 uF, -10+50%, 10 VDCW.	C503	19A702052P14	Ceramic: 0.01 uF +10%, 50 VDCW.
C232	19A702052P14	Ceramic: 0.01 uF +10%, 50 VDCW.	C504	19A702061P29	Ceramic: 22 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM/`C.
C234 C236	19A702052P14 19A702052P14	Ceramic: 0.01 uF ±10%, 50 VDCW. Ceramic: 0.01 uF ±10%, 50 VDCW.	C505	19A702061P25	Ceramic: 18 pF +5%, 50 VDCW, temp coef 0 +30 PPM/ C.
C237	19A702061P17	Ceramic: 12 pF +5%, 50 VDCW, temp coef	C506	19A701534P7	Tantalum: 10 uF ±20%, 16 VDCW.
C238	19A702061P9	0 <u>+</u> 30 PPM/`C	C507 thru	19A702052P14	Ceramic: 0.01 uF <u>+</u> 10%, 50 VDCW.
C239	19A702061P9	0 +60 PPM/'C. Ceramic: 8.2 pF +0.5 pF, 50 VDCW, temp coef	C509	19A702061P6	Ceramic: 2.7 pF ±0.5 pF, 50 VDCW, temp coef
C239		0 <u>+</u> 60 PPM/`C. (Used in Gl,G2).	C511		0 +120 PPM/`C.
C239	19A702061P11	Ceramic: $6.8 \text{ pF} \pm 0.5 \text{ pF}$, 50 VDCW , temp coef $0 \pm 60 \text{ PPM/}$ C. (Used in G3).	C511	19A702052P14 19A702061P1	Ceramic: 0.01 uF ±10%, 50 VDCW. Ceramic: 1 pF ±0.5 pF, 50 VDCW.
C240	19A702061P25	Ceramic: 18 pF \pm 5%, 50 VDCW, temp coef 0 + or -30 PPM/ $^{\circ}$ C.	C513	19A702061P12	Ceramic: 8.2 pF +0.5 pF, 50 VDCW, temp coef
C402	19A702061P41	Ceramic: 39 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/^C. (Used in G1).	C514	19A702061P33	0 ±60 PPM/'C. Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/'C.
C402	19A702061P33	Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM/°C. (Used in G2,G3).	C515	19A702061P29	Ceramic: 22 pF +5%, 50 VDCW, temp coef
C403	19A702061P37	Ceramic: 33 pF +5%, 50 VDCW, temp coef 0 +30 PPM/^c. (Used in G1).	and C516		0 ±30 PPM/`C.
C403	19A702061P17	- Ceramic: 12 pF +5%, 50 VDCW, temp coef 0 +30 PPM/C. (Used in G2).	C517 and C518	19A702052P26	Ceramic: 0.1 uF ±10%, 50 VDCW.
C403 +	19A702061P25	Ceramic: 18 pF +5%, 50 VDCW, temp coef	C519	19A702052P5	Ceramic: 1000 pF <u>+</u> 10%, 50 VDCW.
C404	19A702061P13	0 ± 30 PPM/°C. (Used in G3). Ceramic: 10 pF ± 5 %, 50 VDCW, temp coef	C520	19A702052P14	Ceramic: 0.01 uF <u>+</u> 10%, 50 VDCW.
C404	19A702061P17	0 +30 PPM/'C. (Used in G1).	C521	19A703314P10	Electrolytic: 10 uF -10+50% tol, 50 VDCW; sim to Panasonic LS Series.
C404 *	19A702061P11	Ceramic: 12 pF +5%, 50 VDCW, temp coef 0 +30 PPM/'C. (Used in G2). Ceramic: 6.8 pF +0.5 pF, 50 VDCW, temp coef	C522 C523	19A702052P26 19A702236P8	Ceramic: 0.1 uF ±10%, 50 VDCW. Ceramic: 1.5 pF ±.25 pF, 50 VDCW.
C406	19A702236P11	Ceramic: 6.9 pF ±0.5 pF, 50 VDCW, temp coef 0 ±60 PPM/'C. (Used in G3).			
		Ceramic: 2.7 pF \pm 0.25 pF, 50 VDCw, temp coef 0 \pm 30 PPM/ $^{\circ}$ C. (Used in G1).	D101	19A705377P1	Silicon, Hot Carrier: sim to Motorolla MMB0201.
C406	19A702236P7	Ceramic: 1.2 pF \pm .25 pF, 50 VDCW, temp coef 0 \pm 30 PPM/ $^{\circ}$ C. (Used in G2).	D102 and	19A700028P1	Silicon, fast recovery: fwd current 75 mA, 75 PIV; sim to Type 1N4148.
C406 *	19A702236P9	Ceramic: 1.8 pF \pm 0.25 pF, 50 VDCW, temp coef 0 \pm 30 PPM/ $^{\circ}$ C. (Used in G3).	D103		
C407	19A702061P73	Ceramic: 330 pF <u>+</u> 5%, 50 VDCW, temp coef 0 <u>+</u> 30 PPM/^C.	D104	19J706892P2 19A703588P3	Silicon, pin: sim to Unitrode UM9401. Zener, transient suppressor: sim to 1N6278A.
C408	19A702168P1	Variable, ceramic: 2 to 7 pF, 100 VDCW;	D106	19A702526P2	Silicon. (Schottky Barrier): sim to BAT 17.
C409	19A702061P99	sim to JFD DV2SN7A. Ceramic: 1000 pF +5%. 50 VDCW. temp coef	D202 and	19A702526P2	Silicon. (Schottky Barrier): sim to BAT 17.
C410	19A702236Pl	0 +30 PPM/`C	D203 D401	19J706892P2	Silicon, pin: sim to Unitrode UM9401.
		0 ±30 PPM/°C.			

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

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SYMBOL GE PART NO.		DESCRIPTION	SYMBO	
D501 and	19A700028P1	Silicon, fast recovery: fwd current 75 mA, 75	Q502	
D502		PIV; sim to Type lN4148.	Q503	
J101 thru J103	19B801341P1	RF Jack.	R101	
J201	19A700072P1	Printed wire: 2 contacts rated @ 2.5 amps;	R102	
J501	19A700072P1	sim to Molex 22-03-2021. Printed wire: 2 contacts rated @ 2.5 amps;	R102	
J702	19A704779P11	sim to Molex 22-03-2021. Connector: sim to Molex 22-17-2122.	R102	
J704	19A700072P29	Printed wire: 3 contacts rated at 2.5 amps;	R103A	
J705	19A700072P30	sim to Molex 22-27-2031. Printed wire: 4 contacts rated at 2.5 amps;	R103B	
0.03	1300072130	sim to Molex 22-27-2041.	R104 R105	
			R106	
L101	198800891P6	Coil, RF: .084 uH; sim to Paul Smith SK-890-1.	R107	
L102	19A700024P7	Coil, RF: 330 nH ±10%.	R108	
L103 thru L106	19A704921P1	Coil.	R109	
£130	198800891P1	Coil, RF Choke: sim to Paul Smith SK-890-1.	R110 R111	
and L131			R112	
L201		(Part of PWB 19D902033P1).	R113	
L202	19A705470P6	Coil: sim to Toko 380NB-27nM. (Used in G1,G2).	R114	
L202	19A705470P5	Coil: sim to Toko 380NB-22nM. (Used in G3).	R115	
L203	19A705470P6	Coil: sim to Toko 380NB-27nM. (Used in Gl,G2).	R116	
L203	19A705470P5	Coil: sim to Toko 380NB-22nM. (Used in G3).	R117	
L401A	19B800891P1	Coil, RF Choke: sim to Paul Smith SK-890-1.	R118	
L401B		(Part of PWB 19D902033P1).	R119	
L402 L403	19B800891P1 19B800891P1	Coil, RF Choke: sim to Paul Smith SK-890-1. Coil, RF Choke: sim to Paul Smith SK-890-1.	thru R121	
		(Used in G1,G2).	R202	
L403	19B800890P4	RF: sim to Paul Smith SK-891-1. (Used in G3).	R202	
L404		(Part of PWB 19D902033P1).		
L405 L502	19B800891P1 H343CLP10022	Coil, RF Choke: sim to Paul Smith SK-890-1. Coil, Fixed: 10 uH +10%.	R203	
and L503	H343CBF10022	Colf, Fixed: 10 un <u>+</u> 106.	R204	
L504	198801413P4	Coil, 39 MHz.	R205	
L505	19A700024P19	Coil, RF: 3.3 uH +10%.	R206	
L506	19B801413P4	Coil, 39 MHz.	R207 R208	
thru L508			R209	
L509	19B801415P2	Transformer, 455 KHz.: sim to AEPD 162B3277P17.	and R210	
			R211	
2101		(Part of Heat Sink Assembly 19B801378G3).	R213	
Q102	194703197P2	Silicon, PNP; sim to MMBT4403 Low Profile Pkg.	R214	
Q103	19A704972P1	Silicon, PNP: sim to Motorola 2N4918.	R215	
Q104	19A700076P2	Silicon, NPN.	R216	
Q201	19A704708P2	Silicon, NPN: sim to NEC 2SC3356.	R217	
Q202	19A700059P2	Silicon, PNP.	R218	
Q203	19A700076P2	Silicon, NPN.	R219 R221	
Q204	19A704708P2	Silicon, NPN: sim to NBC 2SC3356.	R221	
Q206	19A700076P2	Silicon, NPN.	R222	
Q207	19A700059P2	Silicon, PNP.	R224	
Q208	19A700023P2 19A702084P2	Silicon, NPN: sim to 2N3904. Silicon, NPN: sim to MPS 2369.	R225	
Q209 and Q210	138,0200492	SILLOUI, NEN: SUN CO MES 4307.	R226	
Q401	19J706019P1	N-Channel, field effect: MOS DUAL GATE;	R227	
	1	sim to BF960.	R228	

N-Type, field effect: sim to MMBFU310.

19A702524P2

GE PART NO.

19A116818P3

19B800607P103

19B800607P470

19B800607P390

19B800607P560

19B800607P821

19B800607P223

19B800607P394 19B800607P123

19B800779P10

19B800607P103

19B800607P562 19B800607P183

19B800607P821

19A701864P4 19B800607P100

19B800607P560

19B800607P330

19B800607P221

19B800607P332

19B800607P102

19B800607P181

19B800607P473

19B800607P101

19B800607P103

19B800607P822

19B800607P222

19B800607P101

19B800607P273

19B800607P333

19B800607P472 19B800607P224

19B800779P4 19B800607P473

19B800607P823

R229

19A700023P2

DESCRIPTION

Channel, field effect: sim to Type 3N1877.

Metal film: 10K ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 47 ohms <u>+</u>5%, 200 VDCW, 1/8 w.

(Used in G1).

Metal film: 39 ohms +5%, 200 VDCW, 1/8 w. (Used in G2).

Metal film: 56 ohms ±5%, 200 VDCW, 1/8 w. (Used in G3).

Metal film: 820 ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 820 ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 22K ohms ±5%, 200 VDCW, 1/8 w. Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 12K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 390K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 2.2K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 10K ohms +5%, 200 VDCW, 1/8 w.

Metal film: 18K ohms <u>+</u>5%, 200 VDCW, 1/8 w. Metal film: 820 ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Thermal: 10K ohms $\pm 10\%$, sim to Midwest Components 2H-103.

Metal film: 10 ohms \pm 5%, 200 VDCW, 1/8 w.

Metal film: 56 ohms \pm 5%, 200 VDCW, 1/8 w. (Used in G1).

Metal film: 33 ohms \pm 5%, 200 VDCW, 1/8 w. (Used in G2,G3).

Metal film: 56 ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 220 ohms +5%, 200 VDCW, 1/8 w.

Metal film: 3.3K ohms +5%, 200 VDCW, 1/8 w.

Metal film: 1K ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 180 ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 47K ohms +5%, 200 VDCW, 1/8 w.

Metal film: 3.3K ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 100 ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 10K ohms +5%, 200 VDCW, 1/8 w.

Metal film: 330 ohms <u>+</u>5%, 200 VDCW, 1/8 w.

Metal film: 8.2K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 2.2K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 100 ohms +5%, 200 VDCW, 1/8 w.

Metal film: 33K ohms +5%, 200 VDCW, 1/8 w.

Metal film: 560K ohms +5%, 200 VDCW, 1/8 w.

Metal film: 220K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 47K ohms ±5%, 200 VDCW, 1/8 w.
Metal film: 22K ohms ±5%, 200 VDCW, 1/8 w.

Metal film: 82K ohms \pm 5%, 200 VDCW, 1/8 w.

------ RESISTORS -----

SYMBOL	GE PART NO.	DESCRIPTION
R230	19B800607P332	Metal film: 3.3K ohms ±5%, 200 VDCW, 1/8 w.
R231	19B800607P472	Metal film: 4.7K ohms +5%, 200 VDCW, 1/8 w.
R232	19B800607P103	Metal film: 10K ohms +5%, 200 VDCW, 1/8 w.
R233	19B800607P332	Metal film: 3.3K ohms +5%, 200 VDCW, 1/8 w.
R234	19B800607P472	Metal film: 4.7K ohms +5%, 200 VDCW, 1/8 w.
R235	19B800607P823	Metal film: 82K ohms +5%, 200 VDCW, 1/8 w.
R236	19B800607P471	Metal film: 470 ohms +5%, 200 VDCW, 1/8 w.
R237 thru R239	19B800607P103	Metal film: 10K ohms <u>+</u> 5%, 200 VDCW, 1/8 w.
R240 thru R242	19B800607P154	Metal film: 150K ohms <u>+</u> 5%, 200 VDCW, 1/8 w
R243	19A702931P137	Metal film: 237 ohms +1%, 200 VDCW, 1/8 w.
R244	19A702931P213	Metal film: 1330 ohms +1%, 200 VDCW, 1/8 w
R245	19B800607P223	Metal film: 22K ohms +5%, 200 VDCW, 1/8 w.
R246	19B800607P102	Metal film: 1K ohms +5%, 200 VDCW, 1/8 w.
R248	19B800607P1	Metal Film: 0 ohms (50 Milli-ohms Max), 1/8
R401 and R402	19B800607P331	Metal film: 330 ohms <u>+</u> 5%, 200 VDCW, 1/8 w.
R403	19B800607P270	Metal film: 27 ohms +5%, 200 VDCW, 1/8 w.
R404	19B800607P683	Metal film: 68K ohms +5%, 200 VDCW, 1/8 w.
R405	19B800607P823	Metal film: 82K ohms +5%, 200 VDCW, 1/8 w.
R406	19B800607P183	Metal film: 18K ohms +5%, 200 VDCW, 1/8 w.
R407	19B800607P101	Metal film: 100 ohms +5%, 200 VDCW, 1/8 w.
R409	198800607P221	Metal film: 220 ohms +5%, 200 VDCW, 1/8 w.
R410	H212CRP915C	Deposited carbon: 1.5 ohms ±5%, 1/4 w. (Used in Gl,G2).
R410 *	H212CRP910C	Deposited carbon: 1 ohm ±5%, 1/4 w. (Used in G3).
R501	19B800607P181	Metal film: 180 ohms +5%, 200 VDCW, 1/8 w.
R502	19B800607P270	Metal film: 27 ohms +5%, 200 VDCW, 1/8 w.
R503	19B800607P682	Metal film: 6.8K ohms +5%, 200 VDCW, 1/8 w
R504	19B800607P270	Metal film: 27 ohms +5%, 200 VDCW, 1/8 w.
R505	19B800607P683	Metal film: 68K ohms +5%, 200 VDCW, 1/8 w.
R506	19B800607P823	Metal film: 82K ohms ±5%, 200 VDCW, 1/8 w.
R507	19B800607P183	Metal film: 18K ohms +5%, 200 VDCW, 1/8 w.
R508 R509	19B800607P101 19B800607P272	Metal film: 100 ohms ±5%, 200 VDCW, 1/8 w. Metal film: 2.7K ohms +5%, 200 VDCW, 1/8 w.
R510	1	
	19B800607P270	Metal film: 27 ohms +5%, 200 VDCW, 1/8 w.
R511 R512	19B800607P473	Metal film: 47K ohms +5%, 200 VDCW, 1/8 w. Metal film: 8.2K ohms +5%, 200 VDCW, 1/8 w.
R512	198800607P822	
R513	198800779P4 198800607P682	Variable, 1K ohms +25%, 100 VDCW, .3 w. Metal film: 6.8K ohms +5%, 200 VDCW, 1/8 v
		<u>- ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '</u>
R515	198800607P821	Metal film: 820 ohms ±5%, 200 VDCW, 1/8 w
U102	1	(Part of Heat Sink Assembly 198801378G3).
U103	19A701789P2	DUAL OP AMP; sim to LM358.
U201	19D901958G3	Voltage Controlled Oscillator. (Used in Gl
U201	19D901958G4	Voltage Controlled Oscillator. (Used in G2
U201	19D901958G5	Voltage Controlled Oscillator. (Used in G3
U202	19A700029P44	Digital: BILATERAL SWITCH.
U203	19A704971P1	Voltage Regulator, 5 volt; sim to: Motoro MC78L05ACP.
U204	198801351P6	Crystal Oscillator, temperature compensate 12.80 MHz. <u>+</u> 5 PPM/`C.
U205	19A704287P2	Voltage Divider: sim to Motorolla MCl2018.
U206	19B800902P4	Synthesizer: CMOS Serial Input.
U207	19A701999P4	Voltage Regulator, positive. sim to LM317L

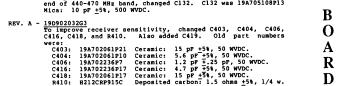
- 1	SYMBOL	GE PART NO.	DESCRIPTION
	U501	19A704619P1	Linear: IF AMPLIFIER AND DETECTOR.
	U502	19A704073P2	Voltage Regulator, positive.
	w101		(Part of PWB 19D902033P1).
	and W102		(Fact of FWB 190902033F1).
	"		
	Y501	19A705376P5	Crystal Unit, fixed frequency: 45.455 MHz.
- 1	Z401	19A705458P4	Filter, UHF: 403-425 MHz.
- 1	Z401	19A705458P1	Filter, UHF: 450-470 MHz.
- 1	Z401	19A705458P2	Filter, UHF: 470-492 MHz.
١	Z402	19B801025P1	Double Balanced Mixer: sim to Mini-Circuits SBL-
١	z501	19A705328P1	Crystal filter, monolithic: 45.000 MHz., sim to Toyocom 45E2B2.
ı	2502	Ī	(Part of Z501).
	2503	19B801021P2	Bandpass filter: 455 kHz <u>+</u> 1.5; sim to Murata CFW-455B.
			HEAT SINK ASSEMBLY 198801378G3
١			
	Q101	19A116742P2	Silicon, NPN.
	U102	19A134717P3	Voltage Regulator, positive; sim to uA7808U.
١			miscellaneous
١	i	19B801490P1	Ground Strap.
		19A702364P106	Machine screw: TORX Drive, No. M2 - 0.4 x 6.
١		19B801382P2	Bracket: Power support. (Used with U101).
l		19B801377G3	Heat Sink.
		19A705469P1	Insulator: Plate. (Used with Heat Sink).
		N402P5B6	Washer: Narrow steel. (Used with Heat Sink).
		N404P11B6	Washer: Internal lock, No 4. (Used with Heat Sink).
		N80P9005B6	Screw: Machine, pan head steel. (Used with Heat Sink).
		19A700068P1	Insulator: Bushing. (Used with Heat Sink).
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PARTSLIST

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for the descriptions of parts affected by these revisions.

REV. A - 1999/20/3261 To improve transmitter operation, changed C3 and C8 and edded C12. C3 and C8 were 19A702061P13 Mica: 10 pP ±5%, 50 WVDC.	R F
REV. A - 19D902032G2 To improve transmitter output power and current drain at top end of 440-470 MHz band, changed C132. C132 was 19A705108P13	1
Mica: 10 pF +5%, 500 WVDC.	В



LBI-31933